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(54) **LIGHT EMITTING CHIP AND PRODUCING METHOD THEREOF, AND LIGHT EMITTING APPARATUS**

(71) Applicants: **BOE MLED Technology Co., Ltd.**, Beijing (CN); **BOE Technology Group Co., Ltd.**, Beijing (CN)

(72) Inventors: **Shanwei YANG**, Beijing (CN); **Junjie MA**, Beijing (CN); **Yuanda LU**, Beijing (CN); **Zhijun XIONG**, Beijing (CN); **Linxia QI**, Beijing (CN); **Jiawei ZHAO**, Beijing (CN); **Yuanhao SUN**, Beijing (CN)

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(57) **ABSTRACT**

The present disclosure provides a light emitting chip and a producing method thereof, and a light emitting apparatus. The light emitting chip includes a patterned substrate; a light emitting unit, wherein the light emitting unit includes an electron injection layer, a luminescent layer and a hole injection layer; a first electrode, wherein the first electrode is connected to the electron injection layer; a second electrode, wherein the second electrode is connected to the hole injection layer; a first passivation layer, wherein the first passivation layer partially covers the light emitting unit, the first electrode and the second electrode, the first passivation layer includes a first opening, and the light emitting unit partially exposes from the first opening; and a heat dissipating layer, wherein the heat dissipating layer covers the first passivation layer, and a part of the light emitting unit exposing from the first passivation layer.